FPD Equipment

Ishihyoki Co., Ltd.

**PI Ink-Jet Coating System**

Full automatic PI ink-jet/prebake system for FPD

- Large size substrate use (G5.5~G9)
- Configuration for various requirements
- High utility efficiency of PI liquid (more than 95%)
- Excellent film uniformity & high-throughput
- Small footprint and weight saving
- Easy & user-friendly control system & software

Y.A.C. Co., Ltd.

**High Density Plasma Etching System**

“COSMO” Series

- High density plasma source (TCP™)
- Wide process window
- Active substrate temperature control (ESC)

SHINDO ENG., LAB. Ltd.

**In-Line Single Substrate Transfer Auto Clave / In-Line Vacuum Laminator for TSP, LCD, OLED (OCA/OCR)**

- Compact Design / Minimized install space
- Fully Automated in-Line system
- Safety
- No need pallet, cassette
- Rapid tact time
**Tempered Glass Cutting System**

- Glass Size: G2~G6
- Glass Thickness: 0.1~1.4mm
- Capability of Cell, Circle, Free-form curve Cutting
- Quality Cutting Edge (Roughness 5um under)
- Stage Speed: Min 500mm/sec
- Sapphire Cutting

**Laser Lift Off System**

- Can cater Excimer and/or UV Laser
- Glass Size: G2~G6
- Various Beam Size
- Stable Lift Off
- Live monitoring on laser beams
  - and OLED Laser Sealing System

**Laser Drilling System**

- PoP Laser Drilling Machine
- 4 Sources 4 Beams
- PRS Pattern Recognition System
- High productivity with effective power control
Related Equipment for Cell, Module Process (in-Line)

- Panel Scriber
- Edge Grinder
- Wet Cleaning equipment
- POL attachment equipment
- Outer Lead Bonder
- FOG, PWB Bonder
- Sealing Dispenser
- Automated Optical Inspection equipment

Double / Single side Flat Surface Grinder

- Excellent Surface Flatness
- High Surface Uniformity
- High stiffness
- High grinding rate
- Low power